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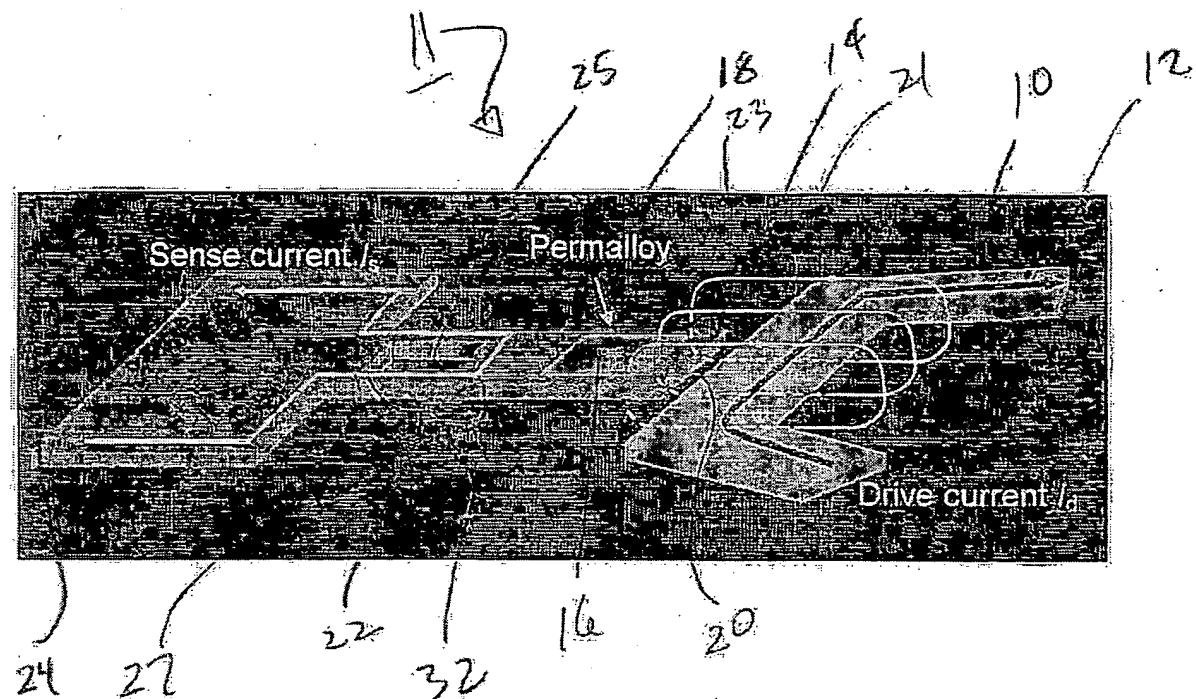
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Fig. 1



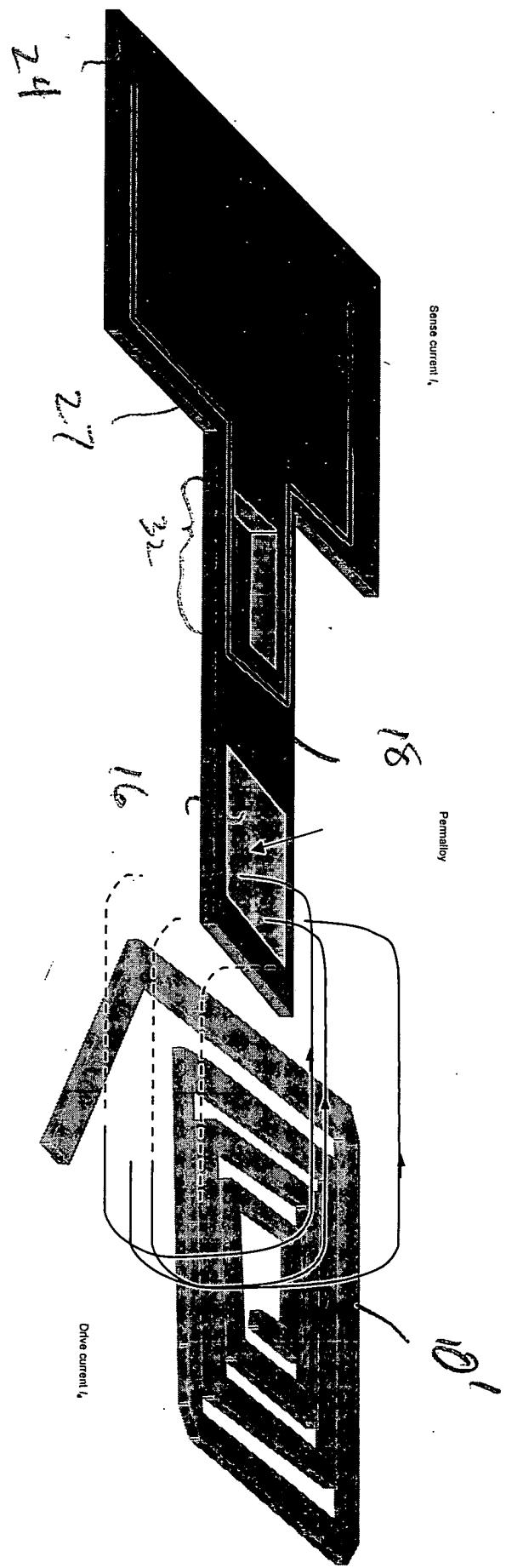


Fig. 2

Fig. B 3

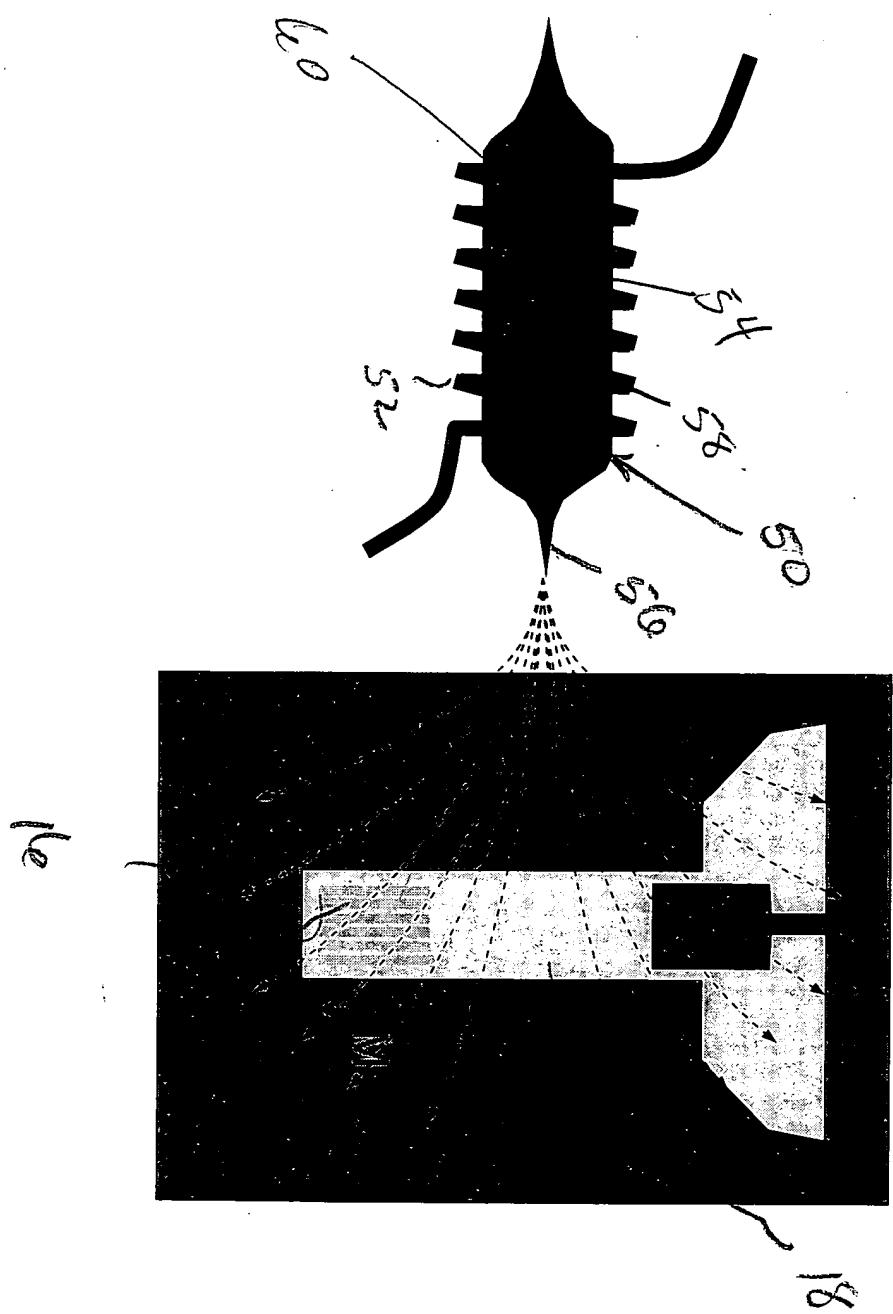


Fig. 4 (a)

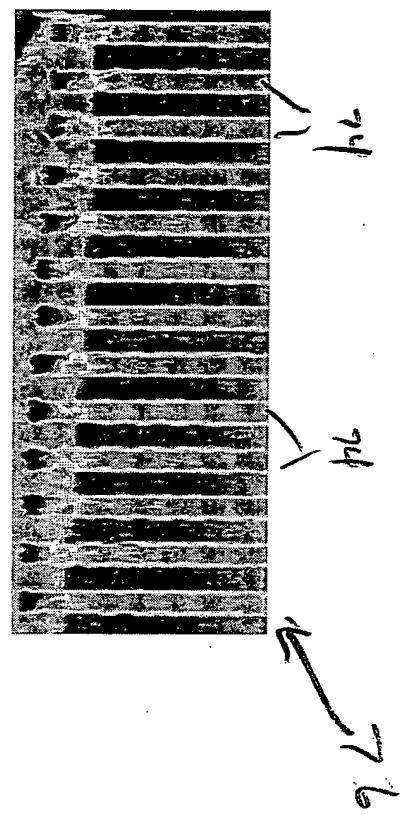
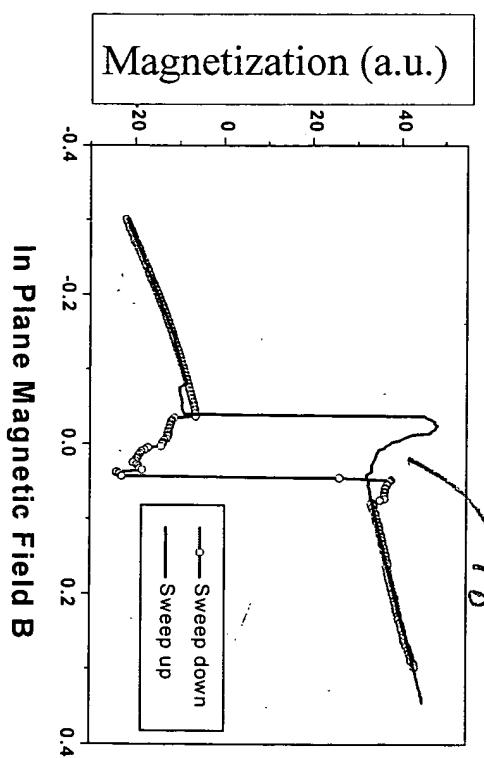
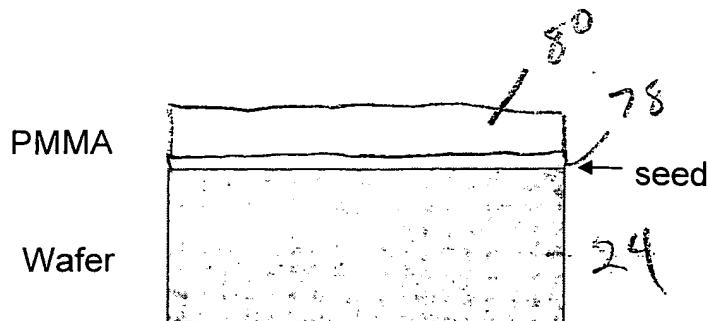
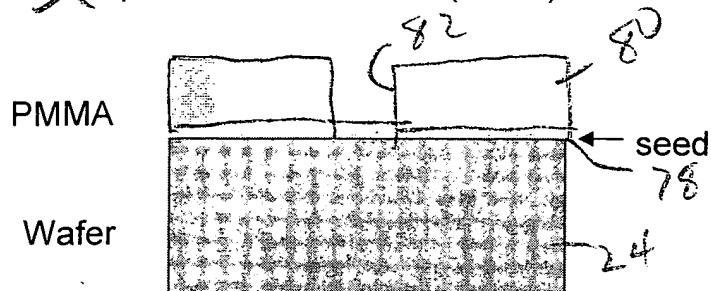


Fig. 4 (b)

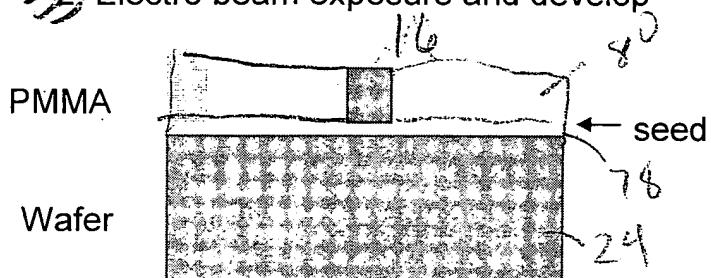




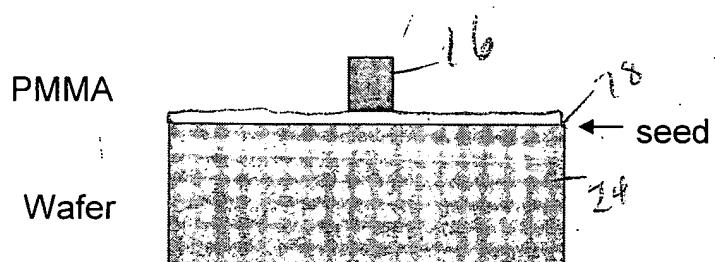
5.1 Spin coat thick PMMA (~2um)



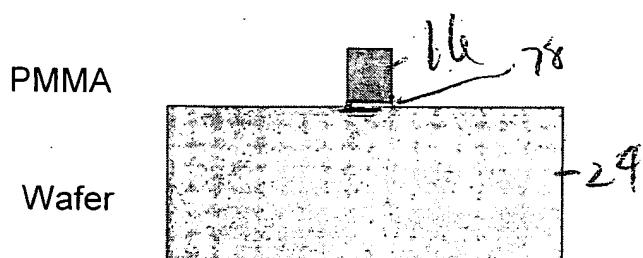
5.2 Electro beam exposure and develop



5.3 Electro beam exposure and develop



5.4 Stripe off PMMA



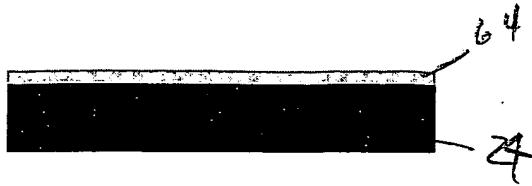
5.5 Dry etch seed metal layer

Fig 5f 11c

CIT 43 KU X2 9, 9 5 4 5 m m

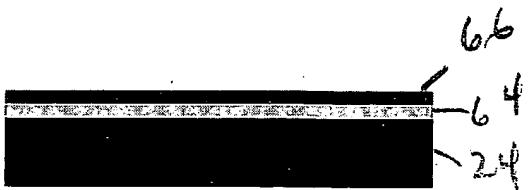
1 2 3 4 5

Fig. 6a



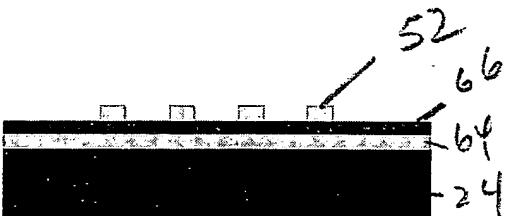
Cu or coating 30 nm

Fig. 6b



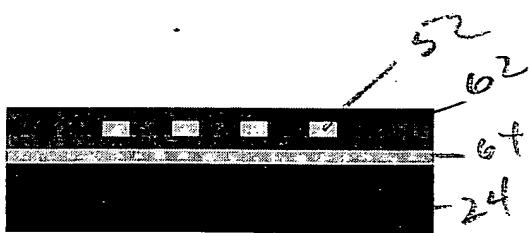
Insulator deposition 1um
SiN or cured photoresist

Fig. 6c



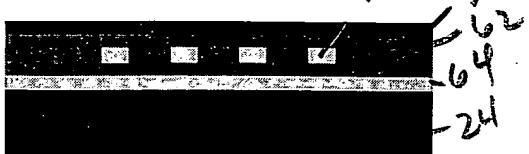
Bottom conductor
Plating, Cu or Au 1um

Fig. 6d



1um Cured Photoresist
Or PECVD SiO₂

Fig. 6e



Electroplate 1um Ni core

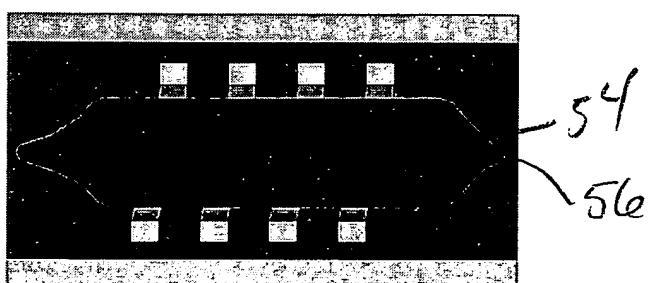
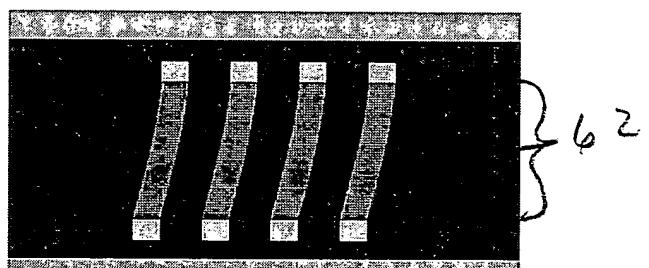
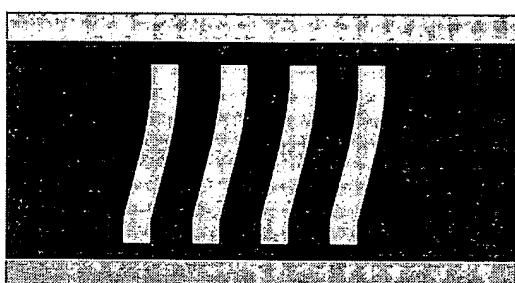
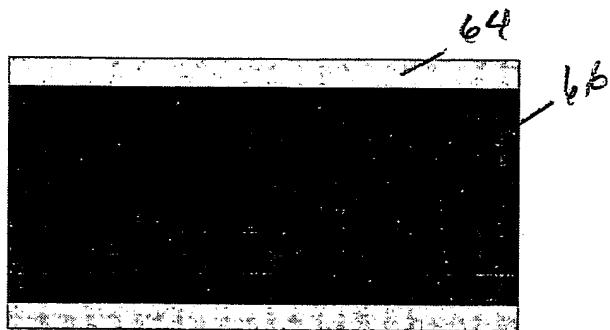
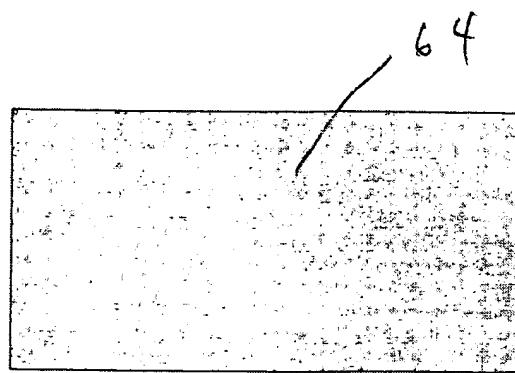
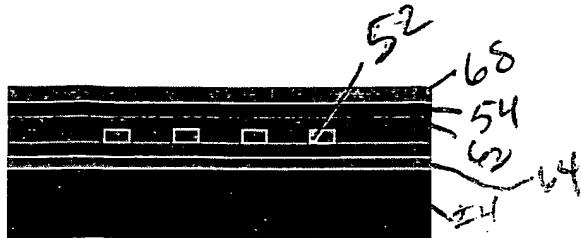


Fig. 6F



1um cured Photoresist
Or PECVD SiO₂

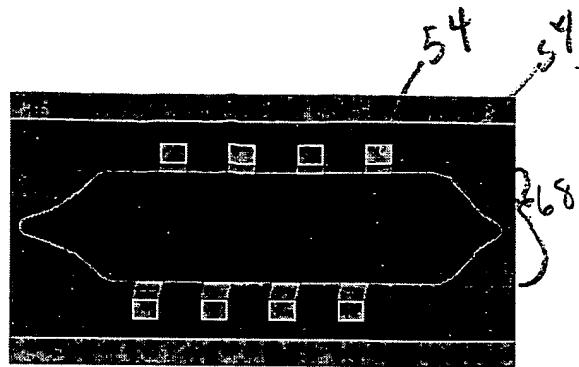
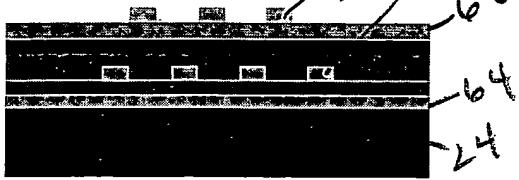


Fig. 6G



Electroplate Cu or Au

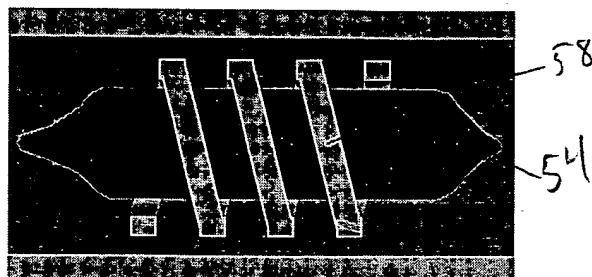
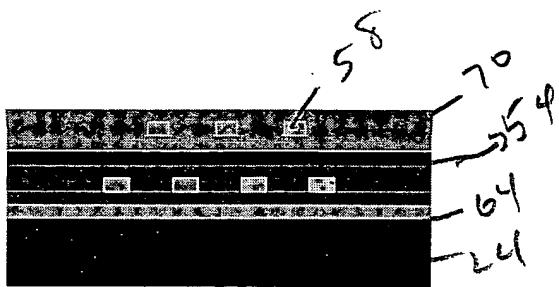


Fig. 6H



Cap Photoresisit or SiO₂

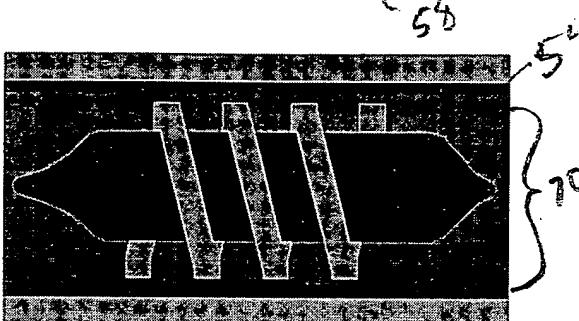
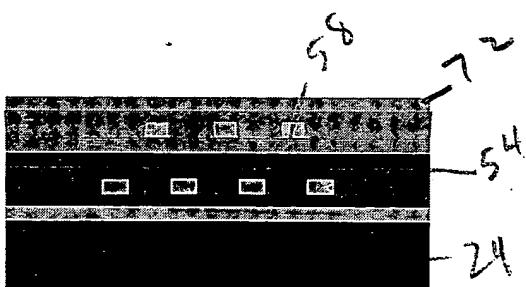


Fig. 6I



Cap with metal/SiN for electrical
shielding / passivation

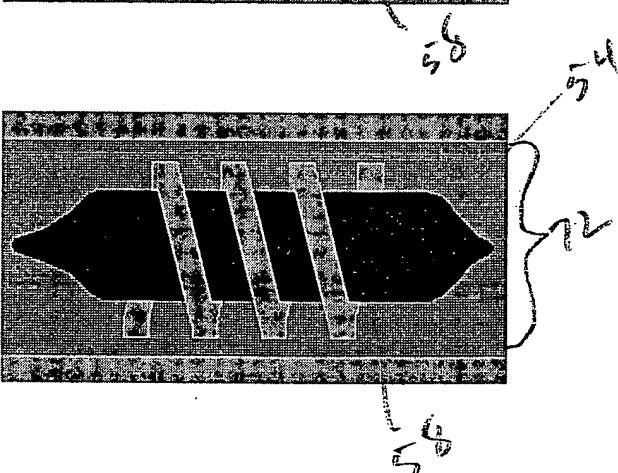


Fig. 7

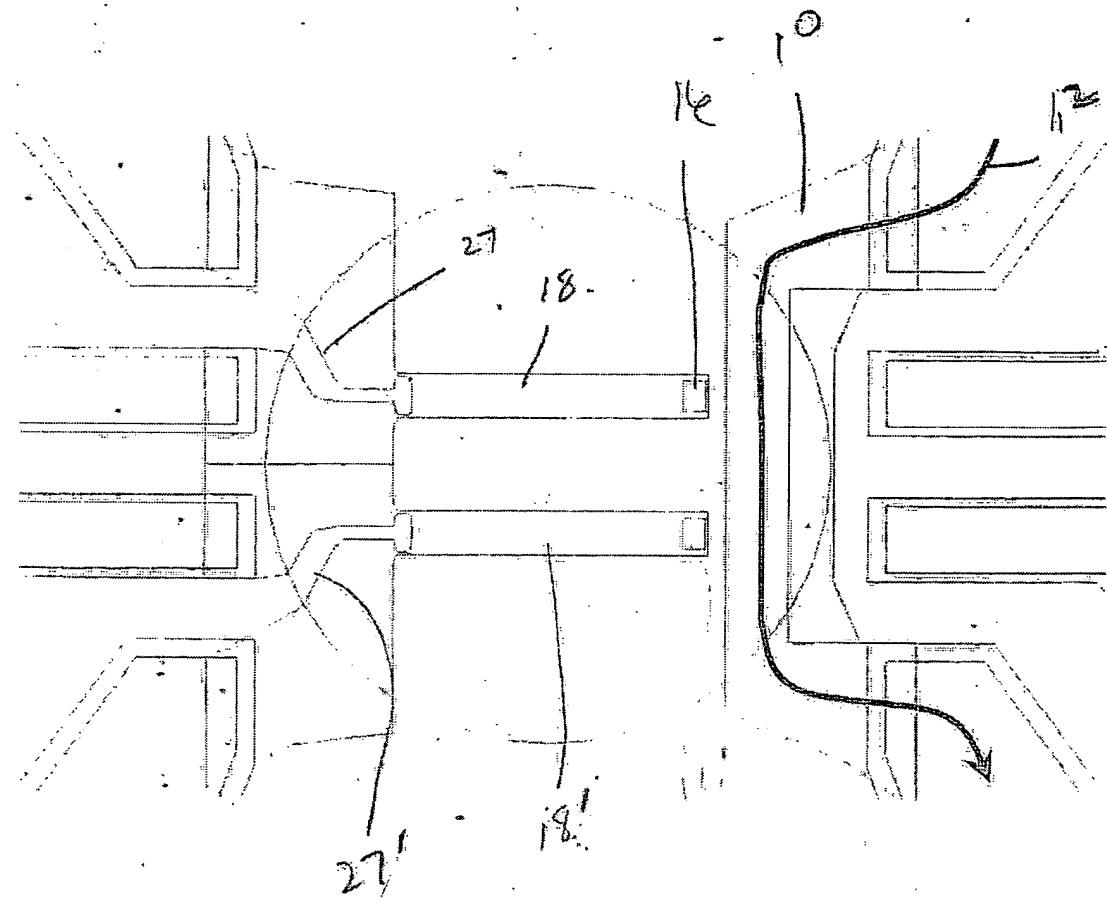


Fig. 8

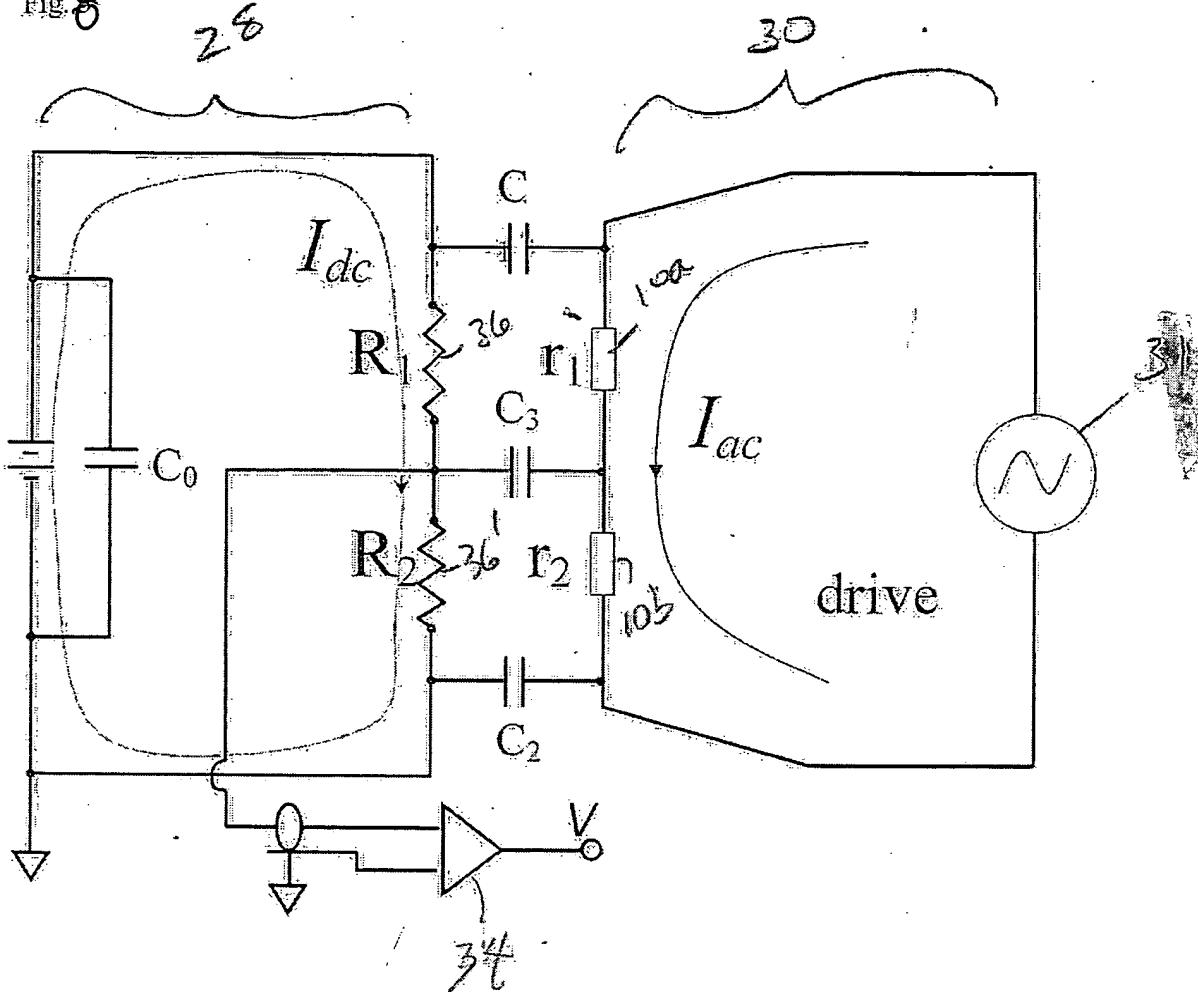


Fig 9a

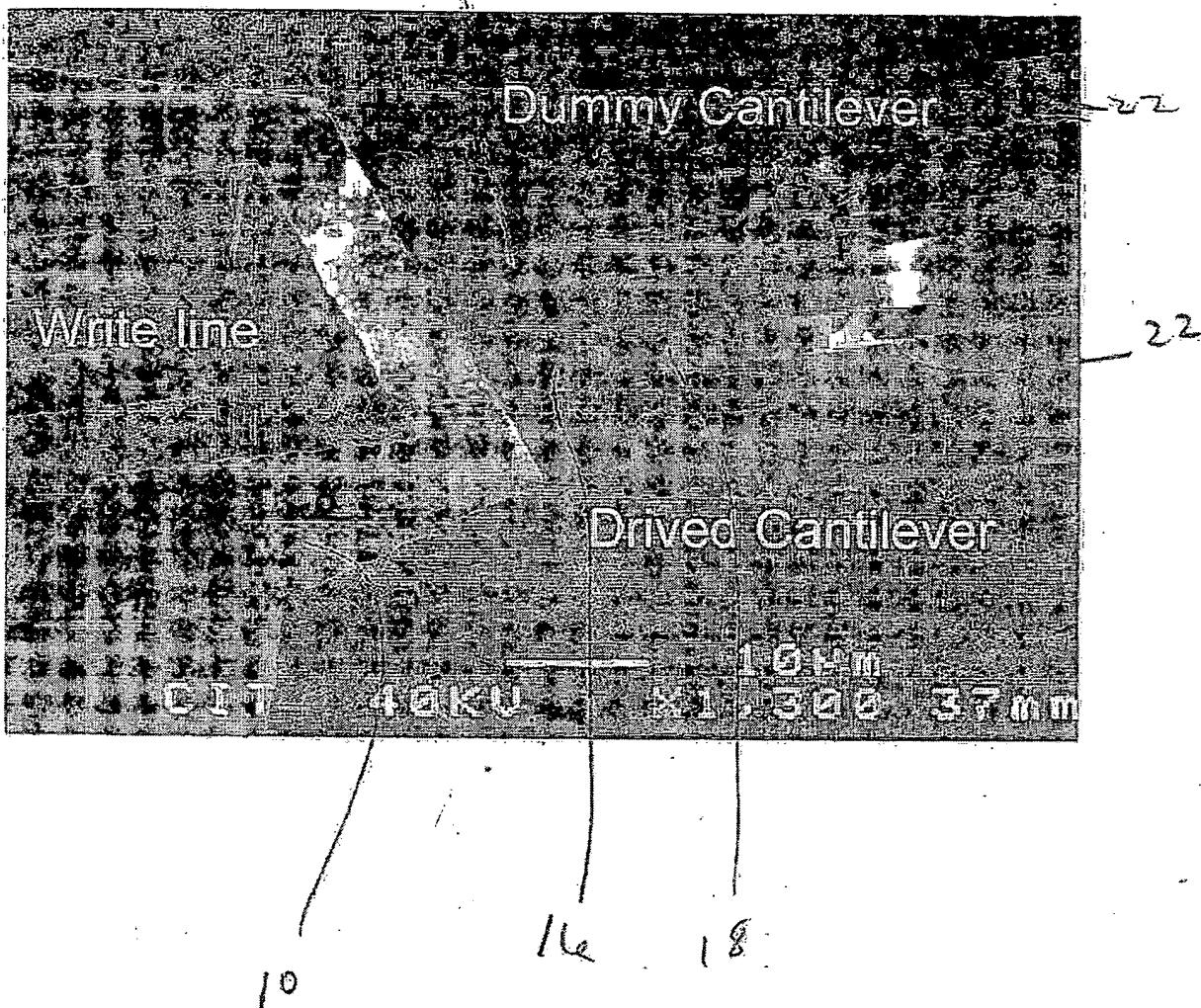


Fig. 9b

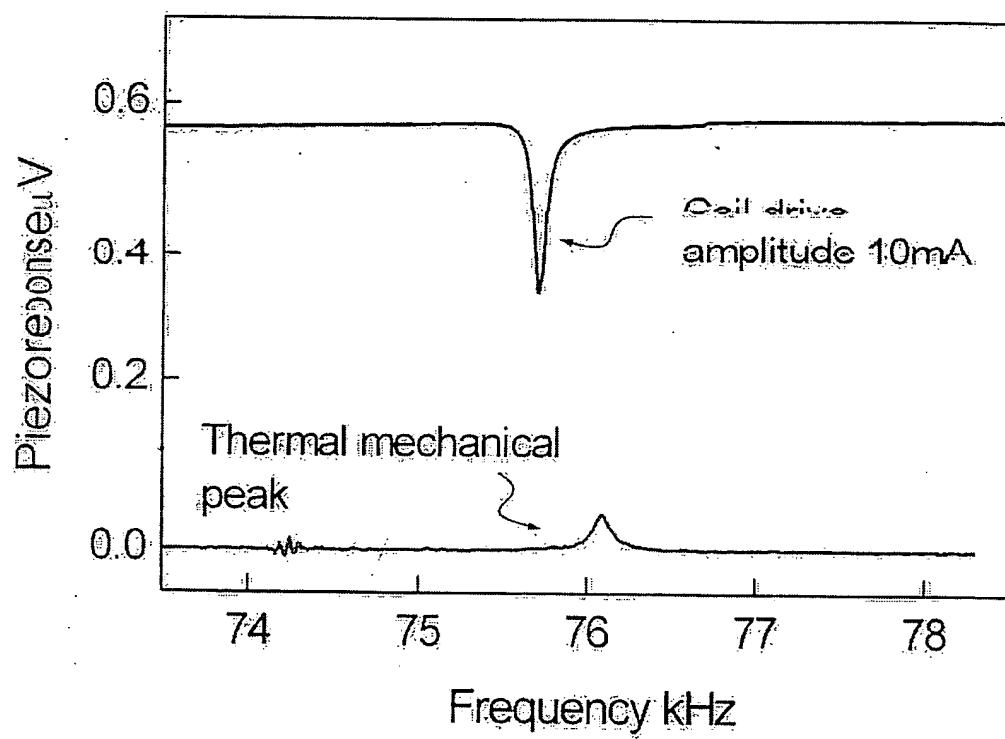


Fig. 10

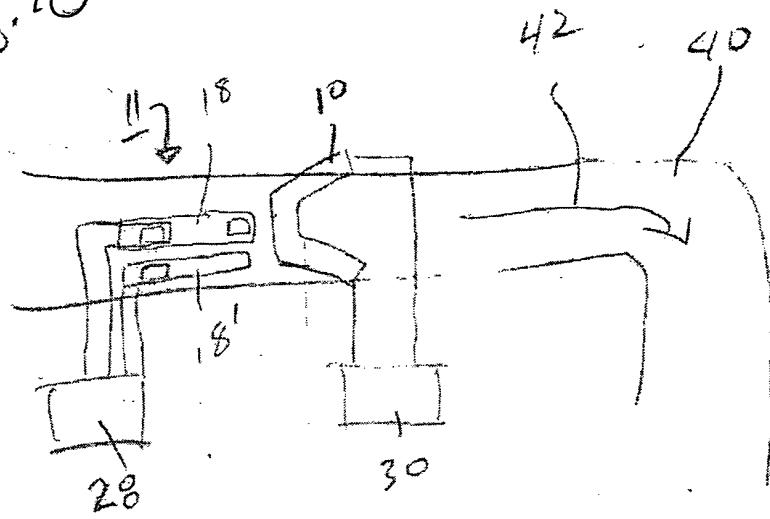


Fig. 11

